

C2225X334KBRAC7800

Aliases (C2225X334KBRAC7800)

SMD Comm X7R HV Flex, Ceramic, 0.33 uF, 10%, 630 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 2225



Click [here](#) for the 3D model.

Dimensions	
Chip Size	2225
L	5.9mm +/-0.75mm
W	6.4mm +/-0.4mm
T	2mm +/-0.20mm
B	0.7mm +/-0.35mm

Packaging Specifications	
Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	500

General Information	
Series	SMD Comm X7R HV Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	430 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.33 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	10%
Voltage DC	630 VDC
Dielectric Withstanding Voltage	945 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	303 MOhms

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